42-DL211

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Optical Fiber Transmitting IC



42-DL211

OPTICAL FIBER TRANSMITTING IC

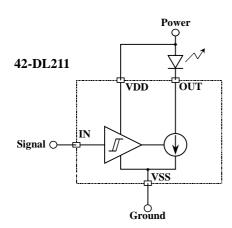
GENERAL DESCRIPTION

42-DL211 is a driver IC designed for the application of high-speed optical fiber transmission. It integrates the LED driver with constant current output to reduce the complexity and the cost of the transmission module. 42-DL211 can transmit with the speed up to 13Mb/s. 42-DL211 are fabricated by using CMOS technology with low power consumption purpose.

FEATURES

- 1. TTL interface compatible
- 2. High speed (up to 13Mb/s)
- 3. Uniform output waveform
- 4. Constant current output
- 5. Low power consumption
- 6. Wide range for Supply Voltage (2.7V-5.5V)

BLOCK DIAGRAM And APPLICATION CIRCUIT



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ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Rating	Unit
Supply Voltage	V_{DD}	-0.5 to +7	V
Input Voltage	Vin	-0.5 to V _{DD} +0.5	V
Operating Temperature	Topr	-40 to +85	င
Storage Temperature	Tstg	-55 to +100	င
Electrostatic Damage	ESD	3.5	kV
Output Sinking Current	Іоит	50	mA

RECOMMENDED OPERATING CONDITIONS

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	$\mathbf{V}_{ ext{DD}}$	2.7	-	5.5	V
High Level Input Voltage	$ m V_{IH}$	2.0	-	V_{DD}	V
Low Level Input Voltage	\mathbf{V}_{IL}	0	-	0.8	V

ELECTRICAL CHARACTERISTICS (V_{DD} =5.0V, TA=25°C, if not mentioned)

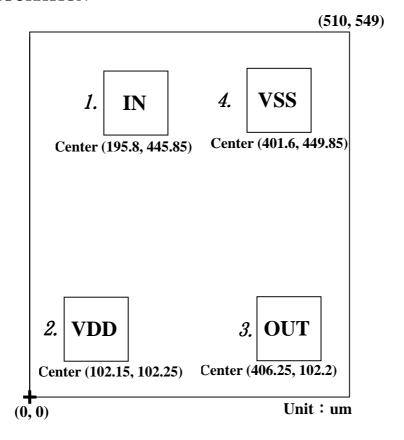
ITEM	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
High Level Input Voltage	V_{IH}	V _{DD} = 3V or 5V	2.0	-	V_{DD}	V
Low Level Input Voltage	$\mathbf{V}_{\mathbf{IL}}$	V _{DD} = 3V or 5V	0	-	0.8	V
Input Leakage Current	I _{IN}	VIN=VDD or VSS	-	-	1	uA
Quiescent Supply Current	I_{DDQ}	V _{IN} =V _{SS}	-	1	3	mA
Output Sinking Current	Iout_on	V _{DD} =3V or 5V, V _{IN} =V _{DD} , V _{FLED} =2.0V	2.4	3	3.6	mA
Output Leakage Current	Iout_off	V _{DD} =3V or 5V, V _{OUT} =3V, V _{IN} =V _{SS}	-	-	5	uA
Propagation Delay	$\mathrm{T}_{\mathrm{PLH}},\mathrm{T}_{\mathrm{PHL}}$	V _{DD} =3V, C _{LED} =15pF, V _{FLED} =2.0V	-	-	100	ns
Rise Time, Fall Time of IOUT	T_r, T_f	V _{DD} =3 V, C _{LED} =15pF, V _{FLED} =2.0V	-	-	10	ns
Pulse Width Distortion	Δtw	CLED=15pF, VFLED=2.0V	- 25	0	25	ns
Jitter of Output Current	Δtj	CLED=15pF, VFLED=2.0V		1	25	ns
Data Rate	FDATA	NRZ Code, Cled=15pF, Vfled=2.0V	-	-	13	Mb/s



PAD DESCRIPTIONS

PAD NO.	PAD NAME	DESCRIPTIONS
1	IN	Input Pad(Active High)
2	VDD	Supply Voltage
3	OUT	Output Pad Sinking Current(Active Low)
4	VSS	Ground

DIE CONFIGURATION



Die Size: 510um * 549um Die Thickness: 12mil(=300um) Pad Size: 100um * 100um

* Note: SiTI reserves the right to improve the device geometry and manufacturing processes without prior notice. Though these improvements may result in slight geometry changes, they will not affect die electrical characteristics and pad layouts.



REQUIREMENTS FOR WAFER DELIVERY

Material: Silicon with P-Substrate

Diameter : 6 inches(≒15cm)

Thickness : 12 mils(≒300um)

Malfunctioned die: Marked with red ink or equivalent marking

HANDLING RECOMMENDATION FOR STATIC ELECTRICITY PROTECTION

- (1) Avoid any circumstance that produce static electricity, e.g. rubbing against plastic, during moving, storing and processing 42-DL211.
- (2) Process 42-DL211 in a clean room with proper temperature and humidity.
- (3) Ground all working machines and workers wear anti-electrostatic ring to ground during processing.
- (4) Avoid contact 42-DL211with bare hands .If unavoided, wear anti-electrostatic ring and use anti-electrostatic tool to pick it up.

GUARANTED TEMPERATURE AND RETENTION CYCLE

(1) The device/wafer 42-DL211 should be stored in the nitrogenous chest. The conditions suggested are as follows:

Temperature = $23\pm3^{\circ}$ C

Relative Humidity = $50\pm10\%$

Minimum nitrogen inflow = 3 liters/minute

- (2) If the device/wafer, 42-DL211 is incidentally exposed to the air, use it for manufacturing as soon as possible.
- (3) Under the storage environment specified in item (1), six-month safe storage period is guaranteed.



The products listed herein are designed for ordinary electronic applications, such as electrical appliances, audio-visual equipment, communications devices and so on. Hence, it is advisable that the devices should not be used in medical instruments, surgical implants, aerospace machinery, nuclear power control systems, disaster/crime-prevention equipment and the like. Misusing those products may directly or indirectly endanger human life, or cause injury and property loss.

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